Gluing

Dennis Sperlich

Humboldt-Universität Berlin / DESY

April 6, 2016



Why are glues so interesing?

- all components of a module are kept together with glue
- ▶ less weight and space than screws or clips (smartphones/tablets ☺)
- but, are we able to qualify a glue for use in the detector upgrades?
 - lightweight
 - easy to handle
 - easy to obtain in all countries related to module production
 - "long" shelf life
 - sticks to: gold, silicon(oxide), Kapton, aluminium(oxide)
 - does not damage ASIC or sensor
 - keeps sticking at $-30\,^{\circ}\mathrm{C}$ for 10+ years
 - survive thermal cycles down to $-30\,^{\circ}\mathrm{C}$
 - radiation tolerant for HL-LHC

Glues for different use cases

ASIC to hybrid

- silicon on one side gold plated copper on other
- transfers heat from ASIC into hybrid
- does not damage ASIC

hybrid to sensor

- passivated silicon on one side Kapton on the other
- transfers heat fram hybrid into sensor
- must not influence electrical properties of sensor
- unusual location of electronics

Features nice to have

- easy + precise application
 - mixing for each module?
 - cleaning of used tools after each module?
- fast curing (components need to be hold in place by vacuum)

Dennis Sperlich (HU/DESY)





ASIC to hybrid

Two choises

Silverepoxy (TRA-DUCT 2903)

- historical reasons
- electrical connectivity of ASIC substrate
- good thermal connectivity
- high viscosity
- best application with stencil

UV curing (DYMAX 6-621, Loctite 3525)

- no electrical connectivity (no influence seen)
- low to medium viscosity (not with stencil)
- best applied with dispenser ((semi)-automatic)
- very fast curing ($\sim 1 \min$)
- no mixing or cleaning of stencil Dennis Sperlich (HU/DESY) Gluing





Epolite FH-5315

Hybrid to Sensor

- historical reasons
- electrical grade epoxy
- high viscosity (depends on time after mixing)

UV glue not yet qualified (being worked on \bigcirc)

- best application with stencil
- cures $\sim 8 \mathrm{h}$





Application with stencil

- high viscosity glues only
- uses stainless steel ($\sim 120\,\mu{
 m m}$) glue template
- steel sits flat on hybrid/ASIC surface
- glue is scquished with spatula in glue pattern
- creates glue pattern with thickness of steel sheet





but

- no perfect seal between hybrid/ASIC and steel
- glue wets surfaces very well
 - \rightarrow some creeps in between steel and hybrid/ASIC
- every swipe pushes more glue between steel and hybrid/ASIC
- if to much, adhesion stroger than holding vaccum
- stencil needs to be cleaned after every glue application

Application with dispenser

- wide rage of viscosities possible
- glue in syringe (black for UV glues)
- carefully chosen stainless steel needle
- ▶ apply air high pressure (3 bar) for a defined time (100 ms - 3s) to back of surringe
- in case of low viscosity glues, hold a small vaccum in case no pressure is applied
- glue amount defined mainly by viscosity, needle diameter and dispensing time
- \blacktriangleright very small dispensing volumes possible ($\ll 1\,\mu l)$
- in case of constant viscosity, high volume repeatability



Curing

components held in place by vacuum

- components are handled with vacuum pick-ups
- to achieve high dimensional accuracy (especially in z direction)

Convential – Time

- usually at room temperature to achive maximal dimensional stability
- \blacktriangleright 2 part glues usually take $\sim 8\,h$ to set
 - otherwise application would be too time critical

UV curing

- UV glues requre "high" power "UV" light in the full glue volume
 - \blacktriangleright "UV" we use $1\,W_{el}\sim 200\,mW~405\,nm$ LEDs
 - ▶ "high power" $1 W_{el}$ per chip, but only small cross section into glue ($80 \mu m \times \sim 1 cm$)
 - LEDs as close as possible at glue joint



Application Video

https://www.youtube.com/watch?v=ypMhwR1vfNg